

# SOT917-2

plastic thermal enhanced very thin quad flat package; no leads; 20 terminals

10 February 2016

Package information

## 1. Package summary

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<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN20
<b>Package type industry code</b>	HVQFN20
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	30-12-2009



2. Soldering

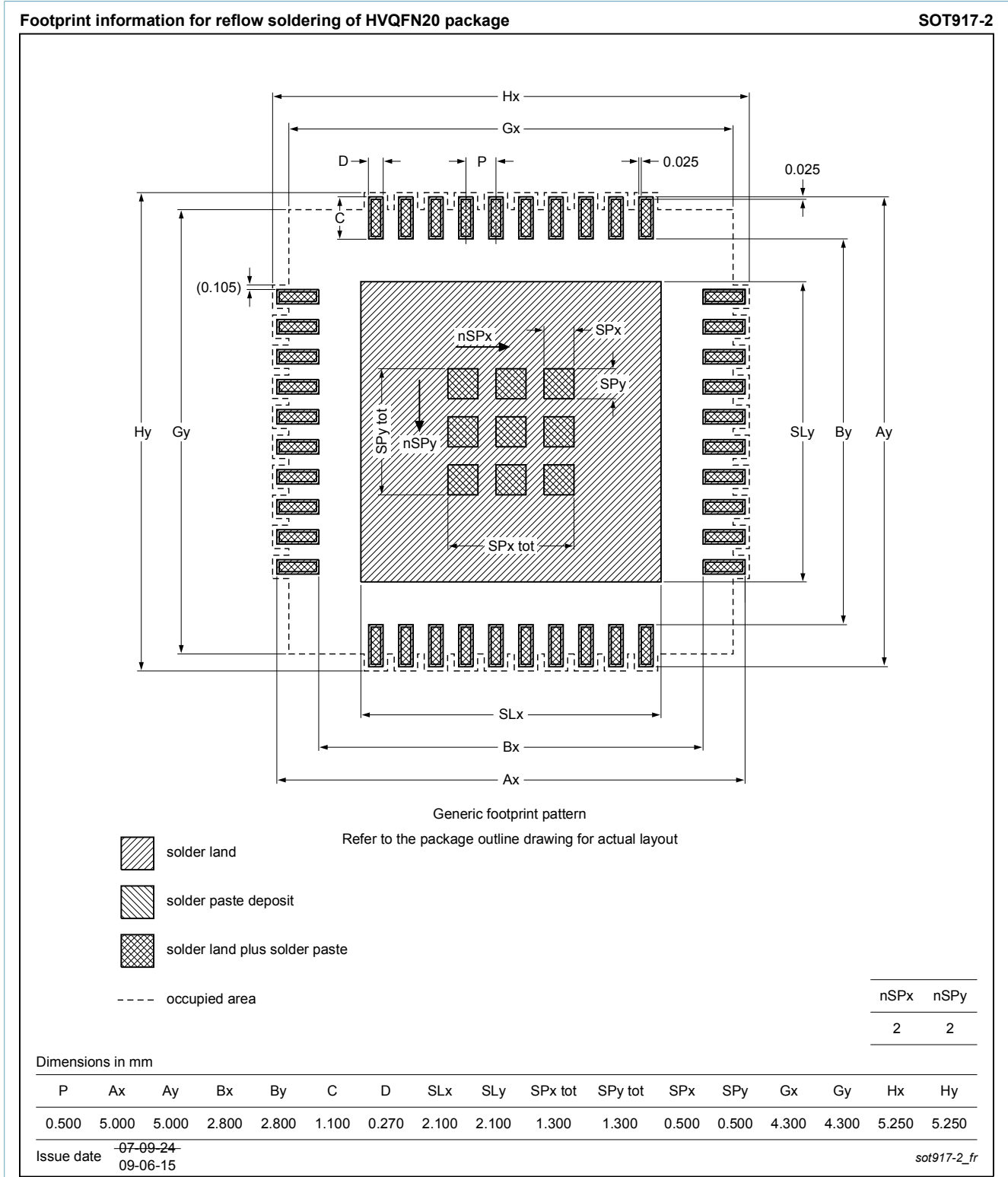


Fig. 1. Reflow soldering footprint for HVQFN20 (SOT917-2)

### 3. Legal information

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